

Title (en)

METHOD FOR PRODUCING FORMED CIRCUIT COMPONENT

Title (de)

VERFAHREN ZUR HERSTELLUNG EINER GEFORMTEN SCHALTUNGSKOMPONENTE

Title (fr)

PROCÉDÉ DE FABRICATION D UN COMPOSANT DE CIRCUIT FAÇONNÉ

Publication

EP 2453040 A4 20130227 (EN)

Application

EP 10797113 A 20100706

Priority

- JP 2010061434 W 20100706
- JP 2009164028 A 20090710

Abstract (en)

[origin: EP2453040A1] Disclosed is a method for producing a formed circuit component, wherein the surface of a substrate is roughened by being irradiated with laser ray instead of being etched using a chemical agent, thereby assuring sufficient adhesive strength with an electroless plating. Specifically disclosed is a method for producing a formed circuit component, which comprises: a first step of forming a substrate (1); a second step of radiating a first laser ray (2) and thereby roughening either a surface of the substrate (1) or only a circuit forming region (1a) of the substrate surface; a third step of applying a catalyst (3) to the surface of the substrate (1); a fourth step of drying the substrate (1); a fifth step of radiating a second laser ray (4), thereby lowering or eliminating the function of the catalyst (3) on a non-circuit forming region (1b); and a sixth step of electroless-plating the circuit forming region (1a) of the substrate surface.

IPC 8 full level

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CPC (source: EP US)

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Citation (search report)

- [A] WO 2008056603 A1 20080515 - ALPS ELECTRIC CO LTD [JP], et al
- [A] US 2003011049 A1 20030116 - NUYTEKENS PETER R [US], et al
- See references of WO 2011004802A1

Designated contracting state (EPC)

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EP 2453040 A1 20120516; **EP 2453040 A4 20130227**; **EP 2453040 B1 20140430**; CN 102471889 A 20120523; CN 102471889 B 20131106; JP 2011017069 A 20110127; JP 4996653 B2 20120808; US 2012107522 A1 20120503; WO 2011004802 A1 20110113

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